



Title of Change:	Qualification of ON Semi, Niigata, Japan for Wafer Bump Process of NCP2811 & NCP2817 Products.
Proposed first ship date:	1 August 2016 <i>or earlier upon customer approval</i>
Contact information:	Contact your local ON Semiconductor Sales Office or <todd.manes@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <mat.hilton@onsemi.com>
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <ken.fergus@onsemi.com>
Type of notification:	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.</p> <p>ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.</p>
Change Part Identification:	Affected products will be identified with marking code of Z.
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Niigata, Japan <input type="checkbox"/> External Foundry/Subcon site(s)
Description and Purpose:	<p>This FPCN is to notify ON Semiconductor’s customers that NCP2811 and NCP2817 family of devices are now qualified at ON Semi Niigata, Japan facility for Wafer Level Chip Scale Package (WLCSP) wafer bumping.</p> <p>The affected devices listed on this FPCN are currently bumped at FCI (FlipChip International, Phoenix, Arizona, USA). Upon expiration of this FPCN, or early upon customer approval, these devices may be processed at either FlipChip International (FCI) or ON Niigata, Japan for Wafer Level Chip Scale Package (WLCSP) wafer bumping.</p> <p>The package outline and electrical performance of the NCP2811 and NCP2817 family of devices bumped at the ON Semi Niigata facility fully meet datasheet specifications. The bump composition from ON Semi Niigata differs slightly from the FCI bump composition and the differences will be made available upon request.</p> <p>Upon expiration of this FPCN, or earlier upon customer approval, FlipChip International (FCI) and ON Niigata will follow the ON Semiconductor standard marking for Wafer Level Chip Scale Package (WLCSP). The Wafer Level Chip Scale Package (WLCSP) bump location can be identified by the assembly code seen on the top side marking.</p> <p><u>Flip Chip International (FCI) assembly code:</u> F</p> <p><u>Niigata assembly code:</u> Z</p>

**Reliability Data Summary:****QV DEVICE NAMES: Package**

NCP2817BFCCT2G WLCSP 12

CAT24C64C4CTR WLCSP 4

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, bias	1008 hrs	0/240
HTSL	JESD22-A103	Ta=150°C	1008 hrs	0/240
TC	JESD22-A104	Ta=-65°C to +150°C	850 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL1 + 3X IR @ 260°C		

Electrical Characteristic Summary:

Electrical characteristics are not impacted. The electrical performance of the NCP2811 and NCP2817 family of devices bumped at the ON Semi Niigata facility fully meet datasheet specifications.

List of Affected Standard Parts:

Part Number	Qualification Vehicles
NCP2811AFCT1G	NCP2817BFCCT2G, CAT24C64C4CTR
NCP2811BFCCT1G	
NCP2817BFCCT2G	